

### **Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

#### **Listing of Claims:**

1. (original) A method used in attaching die to a substrate, comprising:
  - providing a polyimide substrate having a plurality of die attach regions;
  - positioning a dispensing tool having a rectangular aperture adjacent a respective one of the die attach regions, the rectangular aperture having a length greater than a width;
  - positioning the rectangular aperture proximate the respective die attach region;
  - dispensing an epoxy through the rectangular aperture and onto the respective die attach region;
  - translating the dispensing tool in a direction perpendicular to a length of the aperture while dispensing the adhesive to form an epoxy region on the respective die attach region; and
  - attaching a die to the epoxy region, a length of the die approximately equal to the length of the rectangular aperture.
2. (currently amended) The method of Claim 1, wherein the length of the rectangular aperture is between approximately three millimeters and nine millimeters, and a width of the aperture is between approximately 0.09 millimeters and 0.11 millimeters.
3. (original) The method of Claim 1, wherein the width of the aperture is approximately 0.10 millimeters.

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4. (original) The method of Claim 1, wherein positioning the rectangular aperture proximate the respective die attach region comprises positioning the rectangular aperture between 0.10 and 0.11 millimeters from the surface of the respective die attach region.

5-20. (canceled)